

WHAT IS CLAIMED IS:

1. A thin film analyzing method for analyzing a constituent of a thin film, which comprises a cutting step of cutting the thin film obliquely and an analyzing step of analyzing the cut section of the thin film.

2. A thin film analyzing method according to claim 1, wherein the thin film is a thin film formed on a support.

3. A thin film analyzing method according to claim 1, wherein the thin film has a multilayered structure.

4. A thin film analyzing method according to claim 2, wherein the thin film is formed on a support and has a monolayered or multilayered structure.

5. A thin film analyzing method according to claim 1, wherein the analyzing step is a step for measuring a distribution state of a specific component in the cut section of the thin film.

6. A thin film analyzing method according to claim 4, wherein the analyzing step is a step for measuring the distribution state of a specific component in the cut section of the thin film.

7. A thin film analyzing method according to claim 5, wherein the distribution state of the specific component is analyzed by TOF-SIMS in the analyzing step.

8. A thin film analyzing method according to claim 6,

wherein the distribution state of the specific component is analyzed by TOF-SIMS in the analyzing step.

9. A thin film analyzing method according to claim 5, wherein the distribution state of the specific component is analyzed by μ -ESCA in the analyzing step.

10. A thin film analyzing method according to claim 6, wherein the distribution state of the specific component is analyzed by μ -ESCA in the analyzing step.

11. A thin film analyzing method according to claim 1, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

12. A thin film analyzing method according to claim 4, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

13. A thin film analyzing method according to claim 11, wherein an edge angle of the cutting edge made of glass is 55° or less.

14. A thin film analyzing method according to claim 12, wherein an edge angle of the cutting edge made of glass is 55° or less.

15. A thin film analyzing method according to claim 1, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the

surface of the thin film.

16. A thin film analyzing method according to claim 4, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

17. A thin film analyzing method according to claim 1, wherein the thin film is a photosensitive thin film.

18. A thin film analyzing method according to claim 17, wherein the photosensitive thin film is an image recording layer comprising a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant.

19. A thin film analyzing method according to claim 1, wherein the thin film is a photosensitive thin film which is formed on a support and comprises a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant, and in the analyzing step the distributions of the infrared ray absorber and the colorant in the thin film are analyzed.